



DFLS1150Q

1.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER PowerDI123

Product Summary (@+25°C)

| V _{RRM} (V) | I _O (A) | V _F max (V) | I _{R max} (μΑ) | |
|----------------------|--------------------|------------------------|-------------------------|--|
| 150 | 1.0 | 0.82 | 2 | |

Features and Benefits

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Applications

- SMPS
- DC-DC Convert
- Freewheeling Diodes
- Reverse Polarity Protection
- Blocking Diodes

Mechanical Data

- Case: PowerDI[®]123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.01 grams (Approximate)



Top View

Ordering Information (Note 5)

| Part Number | Compliance | Case | Packaging |
|-------------|------------|------------|------------------|
| DFLS1150Q-7 | Automotive | PowerDI123 | 3000/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



F07 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: F = 2018)

M = Month (ex: 9 = September)

Date Code Key

| Year | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | Χ | Y | Z | Α | В | С | D | Е | F | G | Н | I |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|-----------------------------------------------------------------------------------------------------|--------------------------------------------------------|-------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 150 | V |
| RMS Reverse Voltage | V _{R(RMS)} | 106 | V |
| Average Forward Current | I _{F(AV)} | 1.0 | Α |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 50 | A |

Thermal Characteristics

| Characteristic | Symbol | Тур | Max | Unit |
|------------------------------------------------------------------------|-----------------------------------|--------|------|------|
| Thermal Resistance Junction to Soldering Point (Note 6) | $R_{\theta JS}$ | _ | 7 | °C/W |
| Thermal Resistance Junction to Ambient (Note 7) T _A = +25°C | $R_{\theta JA}$ | 125 | _ | °C/W |
| Thermal Resistance Junction to Ambient (Note 8) T _A = +25°C | $R_{\theta JA}$ | 70 | _ | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to | +175 | °C |

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|------------------------------------|--------------------|-----|-----|------|------|------------------------------------------------------------------------------|
| Reverse Breakdown Voltage (Note 9) | V _{(BR)R} | 150 | _ | _ | V | $I_R = 2\mu A$ |
| Forward Voltage | V _F | _ | _ | 0.82 | V | I _F = 1.0A |
| Leakage Current (Note 9) | I _R | _ | _ | 2 | μΑ | V _R = 150V, T _A = +25°C |
| Total Capacitance | Ст | _ | 28 | _ | pF | $V_R = 5V_{DC}$, $f = 1MHz$ |
| Switching Speed | t _{RR} | _ | 13 | _ | ns | I _F = 0.5A, I _R = 1A, I _{RR} = 0.25A (RG1) |

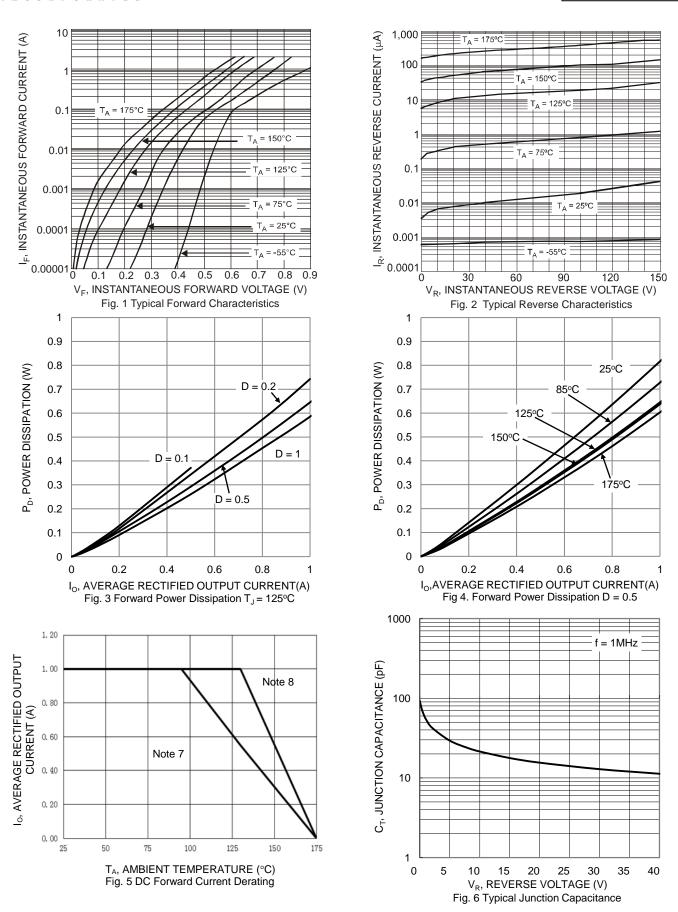
Notes:

- 6. Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
- 7. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

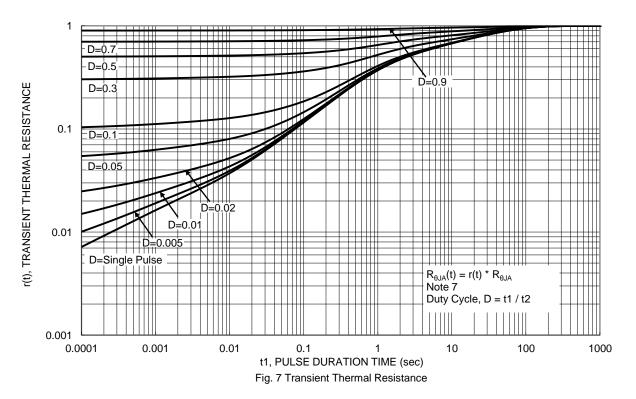
 8. Part mounted on 1inch sq. copper pad, 2oz.

 9. Short duration pulse test used to minimize self-heating effect.







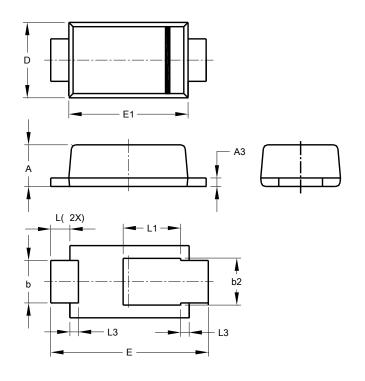




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI123

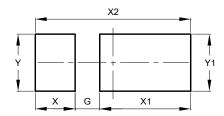


| PowerDI123 | | | | | | | |
|----------------------|-------|-------|------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.93 | 1.00 | 0.98 | | | | |
| A3 | 0.15 | 0.25 | 0.20 | | | | |
| b | 0.85 | 1.25 | 1.00 | | | | |
| b2 | 1.025 | 1.125 | 1.10 | | | | |
| D | 1.63 | 1.93 | 1.78 | | | | |
| Е | 3.50 | 3.90 | 3.70 | | | | |
| E1 | 2.60 | 3.00 | 2.80 | | | | |
| L | 0.40 | 0.50 | 0.45 | | | | |
| L1 | 1.25 | 1.40 | 1.35 | | | | |
| L3 | 0.125 | 0.275 | 0.20 | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI123



| Dimensions | value | | |
|----------------|---------|--|--|
| Dillicitatoria | (in mm) | | |
| G | 0.65 | | |
| Х | 1.05 | | |
| X1 | 2.40 | | |
| X2 | 4.10 | | |
| Y | 1.50 | | |
| Y1 | 1.50 | | |



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